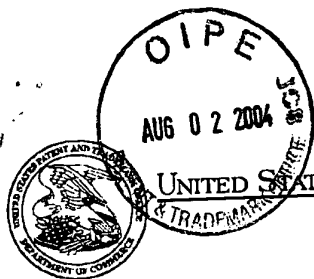


IFW ✓



UNITED STATES PATENT AND TRADEMARK OFFICE

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APPLICATION NUMBER	FILING OR 371 (c) DATE	FIRST NAMED APPLICANT	ATTORNEY DOCKET NUMBER
10/826,713	04/16/2004	William D. Boyd	TI-37214

CONFIRMATION NO. 2185

FORMALITIES LETTER



\*OC000000013078077\*

23494  
 TEXAS INSTRUMENTS INCORPORATED.  
 P O BOX 655474, M/S 3999  
 DALLAS, TX 75265

Date Mailed: 06/28/2004

## NOTICE TO FILE MISSING PARTS OF NONPROVISIONAL APPLICATION

FILED UNDER 37 CFR 1.53(b)

*Filing Date Granted*

### Items Required To Avoid Abandonment:

An application number and filing date have been accorded to this application. The item(s) indicated below, however, are missing. Applicant is given **TWO MONTHS** from the date of this Notice within which to file all required items and pay any fees required below to avoid abandonment. Extensions of time may be obtained by filing a petition accompanied by the extension fee under the provisions of 37 CFR 1.136(a).

- The oath or declaration is unsigned.
- To avoid abandonment, a late filing fee or oath or declaration surcharge as set forth in 37 CFR 1.16(e) of \$130 for a non-small entity, must be submitted with the missing items identified in this letter.

The application is informal since it does not comply with the regulations for the reason(s) indicated below.

The required item(s) identified below must be timely submitted to avoid abandonment:

- Replacement drawings in compliance with 37 CFR 1.84 and 37 CFR 1.121 are required. The drawings submitted are not acceptable because:
  - The drawings must be made on paper that has a white background (see 37 CFR 1.84 (e)). For example, drawings on graph paper, lined paper, or paper that has a non-white background are not acceptable. See Figure(s) 4.

### SUMMARY OF FEES DUE:

Total additional fee(s) required for this application is **\$130** for a Large Entity

- **\$130** Late oath or declaration Surcharge.


08/03/2004 WASFAW1 00000091 200668 10826713  
 01 FC:1051 130.00 DA

Replies should be mailed to: Mail Stop Missing Parts

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

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*A copy of this notice MUST be returned with the reply.*

  
\_\_\_\_\_  
Customer Service Center  
Initial Patent Examination Division (703) 308-1202

PART 2 - COPY TO BE RETURNED WITH RESPONSE



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

William D. Boyd, et al.

Docket No.: TI-37214

Art Unit: 2811

Serial No: 10/826,713

Filed: 04/16/04

For: Wafer-Level Assembly Method for Chip-Size Devices Having Flipped Chips

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

*Karen Vertz*  
Karen Vertz

*7-28-04*  
Date

**RESPONSE TO NOTICE TO FILE MISSING PARTS OF APPLICATION**

Dear Sir:

In response to the Notice of Missing Parts dated June 28, 2004 please charge the fee of \$130.00 for the surcharge under 37 CFR 1.27 to Deposit Account No. 20-0668 of Texas Instruments Incorporated.

Please find enclosed the Declaration/Power of Attorney (2 pages), an Assignment with Form PTO 1595 and formal drawings for the above-referenced case. The Commissioner is hereby authorized to charge any additional fees which may be required. **This sheet is submitted in triplicate.**

Respectfully submitted,

*Yingsheng Tung*  
Yingsheng Tung  
Attorney for Applicants  
Reg. No. 52,305

Texas Instruments Incorporated

Mail Station 3999

P.O. Box 655474

Dallas, TX 75265

Phone: (972) 917-5355



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): William D. Boyd, et al.

Art Unit: 2811

Serial No.: 10/826,713

Examiner: TBD

Filed: 04/16/04

Docket: TI-37214

For: Wafer-Level Assembly Method for Chip-Size Devices Having Flipped Chips

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Karen Vertz  
Karen Vertz

7-28-04  
Date

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed are **FIVE (5)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated  
P.O. Box 655474 M/S 3999  
Dallas, Texas 75265  
Phone: (972) 917-5355

Respectfully submitted,

Yingsheng Tung  
Yingsheng Tung  
Reg. No. 52,305  
Attorney for Applicants